

LPC-965 - RUGGED FANLESS MINI PC WITH DUAL REMOVABLE DRIVES (WIDE RANGE TEMPERATURE)



\$2,810.00 USD

Wide Temperature Fanless PC with Dual Removable Drives

- Powerful Intel® 9th Generation Core™ i3, i5, i7 & Xeon processors
 - ECC Memory Support
- Supports up to 4K resolution, Triple Display support
 - 8 Network Ports (4 POE+, 2 SFP, 2 Standard)
 - 16 DIO (8 In/ 8 Out Digital input/output) ports
 - Dual Removable Front Drives
- Wide Operating Temp (-40°C to 75°C / -40°F to 167°F)
 - Wide Range 6-36 VDC Input, ideal for mobile/field
 - Wall, VESA, & DIN Rail mounting
 - Windows 10 / 10 IoT, Server 2019, and Linux
- RoHS, CE & FCC, EN50121-3-2, EN50155 certified
 - Rackmount model version also available



GALLERY IMAGES



PRODUCT DESCRIPTION

The new Stealth LPC-965 Wide Temperature Mini PC is the leading edge in small form factor computing. It features Intel® 9th Generation Core™ i3, i5, i7 & Xeon processors and supports operation in temperatures ranging from -25°C – 60°C. Packed with robust capabilities, it makes it ideal for a large variety of demanding applications.

Fanless by design, the LPC-965 can be configured with 256GB to 4TB of total SSD storage (using dual drives), as well as 8GB to 64GB of RAM. ECC memory is also available.

This mini PC includes, Dual Removable Front Drive Bays that provide easy drive swapping and onboard Raid supporting 0/1 set-up options. The LPC-965 powerful small form factor PC comes standard with 8 Gigabit LAN Ports, including 4 POE+ and 2 SFP Ports. An abundance of I/O includes USB 3.0, RS232 Serial, 32 DIO (Digital input/output), external SIM card sockets for wireless connectivity and audio/video ports.

Engineered to be extremely mobile friendly, the LPC-965 includes a Wide Range 6-36 VDC power input with a rear locking 3-Pin Ignition Switch. A TPM 2.0 (Trusted Platform Module) is also incorporated to provide increased hardware security.

The LPC-900 series is RoHS, CE & FCC certified, and designed for use in a multitude of applications including: Audio/Video Recording, Embedded Control, Digital Signs, Interactive Kiosks, IoT, Industrial Internet of Things (IIoT), Thin-Clients, and Human/Machine Interface.

ADDITIONAL INFORMATION

Processor

Supporting Intel® Core™ 9th Generation, and Xeon® Processors
Intel® Celeron® G4900T (2 Cores / 2 Threads, 2.9Ghz)
Intel® Pentium® Gold G5400T (2 Cores / 4 Threads, up to 3.1Ghz)
Intel® Core™ i3-9100TE (4 Cores / 4 Threads, up to 3.2Ghz)
Intel® Core™ i5-9500TE (6 Cores / 6 Threads, up to 3.6Ghz)
Intel® Core™ i7-9700TE (8 Cores / 8 Threads, up to 3.8Ghz)
Intel® Xeon® E-2278GEL (8 Cores / 16 Threads, up to 3.90Ghz)

BIOS

AMI

Chipset

Intel® C246

Memory

2x DDR4 Memory Sockets Supporting up to 64GB of RAM / Memory
Optional ECC Memory Support (available for Celeron, Pentium, Core
i3 and Xeon CPUs only)

Internal Storage

256GB TLC SSD (Solid State Drive) Wide Temp standard (SATA)
Options of up to 2TB SSD internal storage.
Optional Onboard RAID configurations (0, 1), requires multiple
drives

Internal Expansion Option

(1) M.2 A-E Key 2230 Slot
(1) M.2 M-key, 2280
2 Internal full sized Mini-PCIe expansion slots

Video

Intel® HD Graphics 610 (Intel® Celeron and Pentium Processors)
Intel® HD Graphics 630 (Intel® 9th Generation and Xeon
Processors)
DisplayPort: Up to 4096 x 2304 @ 60Hz
DVI-D: Up to 1920 x 1080 @ 60Hz
DVI-I: Up to 1920 x 1200 @ 60Hz

Networking

LAN1: Intel® I219LM
Intel® iAMT 12.0 Support (Lan 1)
LAN2: Intel® I210
LAN3: Intel® I210, POE+ (802.3at 25.5W @ 48V)
LAN4: Intel® I210, POE+ (802.3at 25.5W @ 48V)
LAN5: Intel® I210, POE+ (802.3at 25.5W @ 48V)
LAN6: Intel® I210, POE+ (802.3at 25.5W @ 48V)
LAN7: Intel® I350 SFP Port
LAN8: Intel® I350 SFP Port
PXE (Pre-Boot Execution Environment) Support
WoL (Wake On Lan) Support
Optional 802.11 b/g/n/ac Dual Band (2.4Ghz / 5Ghz) Wireless
Networking and Bluetooth 4.0, Realtek® RTL8821AE via internal
Mini-PCIe

Audio

Integrated Realtek High Definition Audio CODEC ALC892, 5.1
Channel HD Audio

Operating Systems

Windows Server 2019
Windows 10 IoT Enterprise
Windows 10 (64-bit)
Ubuntu Linux

TPM Module

TPM 2.0 (Trusted Platform Module), provides increased hardware
security.

Chassis Description

Fanless Rugged Aluminum Chassis

Power Input

Input: 6V – 36V DC
Rear Locking 3-Pin Ignition Switch (12V or 24V)
Rear Locking 3-Pin power Jack ideal for mobile applications
280W AC Adapter

Included with System

North American Power Cord
Wall Mount Bracket
* NOTE: Subject to change without notice
16x DIO (Digital input / output) with Isolation

Rear Panel

4 x RJ45 GB Network PoE+ Ports
4x RS232 COM ports
Rear Locking 3-Pin Ignition Switch (12V or 24V)
2 x USB 3.0 Ports

Front Panel

(2) Removable 2.5" Drive Bays
(2) SIM Communication Slots (3G / LTE)
1 x CFast Socket with Push-in/Pull-out Ejector
1x Display Port Video Connector
1x DVI-D video connector
1x DVI-I Video Connector
2 x SFP Network Ports
2x Gigabit RJ45 Network connections
4x USB 3.0 Ports
Audio Line-Out Jack
Microphone Input Jack
Power and Hard Drive notification LED
Power-on button with LED
Reset button

Dimensions

10.2" (W) x 6.9" (L) x 3.1" (H) (260mm x 175mm x 79mm)

Operating Temperature: -40°C to 75°C (-40°F to 167°F)

Storage Temp: -40°C to 85°C (-40°F to 185°F)

Environmental

Shock: IEC 60068-2-27, SSD: 50G @ wallmount, Half-sine, 11ms

Vibration: IEC 60068-2-64, SSD: 5Grms, 5Hz to 500Hz, 3 Axis

Humidity: 5% ~ 95%, non-condensing (Operating & Non-Operating)

EN50121-3-2

EN50155

Approvals

RoHS

CE

FCC

Weight

Unit Weight: 10.14 lbs / 4.6 KG (Depending on configuration)

Warranty

2 Year limited Warranty, Standard

1 Year Extended Warranty available (see Configurator/Price List)

Disclaimer

Note: Specifications are subject to change without notice.